

Minutes of the Joint ECA Soldering Technology Committee (STC)

Tuesday, April 25, 2006

Ft. Lauderdale, FL

The scope of the Soldering Technology Committee (STC): The STC encompasses soldering practices (soldering iron-mass reflow techniques) and associated soldering materials (solders, pastes and adhesives, and flux/cleaning agents). However, the Committee will focus on solderability test method development for printed through-hole (PTH) and surface mountable components. One of the major functions is to promote commonality and standardization of soldering test methodology within the EIA Sectors.

The meeting was called-to-order at 1:30 PM by STC Committee Chairman, Doug Romm.

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Voting members

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The committee spent the entire meeting time focused on review of revision to J-STD-002. Publication of updated J-STD-002 is a major item that this committee and IPC/JEDEC committees are striving towards this year.

3.1 Replacement for Steam Preconditioning

The team tabled plans for a study to look at possible replacement for steam preconditioning. The team agreed that we will develop a test plan at the next meeting, after completion of major activity for update to J-STD-002.

3.2 Gauge R&R for wetting balance test

The wetting balance test method is currently listed in ANSI/J-STD-002 under the section "Tests without Established Accept/Reject Criterion". Input from Dave Hillman was that the IPC committee discussed the options of either validating or removing the wetting balance method as an accepted method. The team agreed that we will develop a test plan at the next meeting, after completion of major activity for update to J-STD-002.

4 Next meeting

The next meeting is scheduled to be held in conjunction with the ECA Fall 2006 ECA Engineering Summit. ECA Engineering Summit will be held at the Silver Legacy Resort in Reno, Nevada week of September 25-28, 2006.

5 Adjournment

The Committee moved, seconded, and unanimously agreed to adjourn at 5:00PM.

This meeting was conducted in accordance with the EIA legal guidelines and the EIA manual of organization and procedure.

Doug Romm

STC Chairperson